Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: HONG YU YU, MING-FU LI, DIM-LEE KWONG, LAKSHMI KANTA BERA

For:

A THERMAL ROBUST SEMICONDUCTOR DEVICE USING HFN AS METAL GATE ELECTRODE AND THE

MANUFACTURING PROCESS THEREOF

Enclosed are:							
х	4 sheets of drawing(s) - formal.						
x	An assignment of the invention to National University of Singapore and Agency For Science, Technology and Research						
	An associate power of attorney Applicant claims small entity status						
	Request & Certification under 35 USC 122(b)(2)(b)(i)						
The filing fee has been calculated as shown below:							
	(Col. 1) (Col. 2)		(Col. 2)	OTHER THAN A SMALL ENTITY			
FOR:		NO. FILED	NO. EXTRA	RATE	FEE		
BASIC	FEE	><	$\geq \leq$		\$ 770.		
TOTAL	. CLAIMS	34 -20=	14	x 18 =	\$ 252.		
INDEP	CLAIMS	4 -3=	1	x 86 =	\$ 86.		
				SUB TOTAL	\$ 1,108.		
				ASSIGNMENT	\$40.		
				TOTAL	\$ 1.148.		
x	Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,148. A duplicate copy of this sheet is enclosed.						
х	The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any						
overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed. X Any additional filing fees required under 37 CFR §1.16.							
	Respectfully submitted,						
	STEPHEN B. ACKERMAN, REG. NO. 37,761						

EXPRESS MAIL CERTIFICATE

Express Mail No.EV319114250US

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA, 22313-1450. Applicant and/on Attorney requests the date of deposit as the Filing Date.

S17/04 Date of deposit

Signature Pare

10/802